

BAT46WS

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150mA Surface Mount Small Signal Schottky Diode 100V

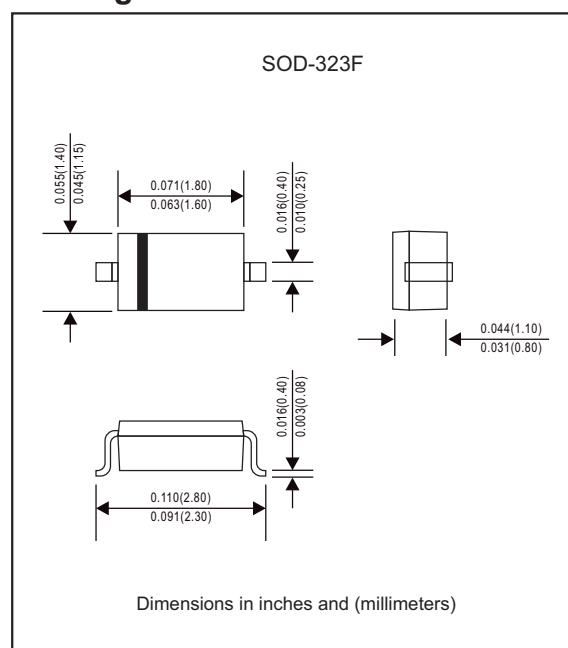
Features

- High breakdown voltage
- Low turn-on voltage
- Guard ring construction for transient protection
- Surface mount device
- Lead-free parts meet RoHS requirements
- Suffix "-H" indicates Halogen-free part, ex.BAT46WS-H

Mechanical data

- Epoxy:UL94-V0 rated flame retardant
- Case : Molded plastic, SOD-323F
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity : Indicated by cathode band
- Mounting Position : Any
- Weight : Approximated 0.008 gram

Package outline



Maximum ratings (AT T_A=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Repetitive peak reverse voltage	V _{RRM}	100	V
Working peak reverse voltage	V _{RWM}	100	V
Forward continuous current (Note 1)	I _F	150	mA
Repetitive peak forward current (Note 1) @ t _p < 1.0s, duty cycle < 50%	I _{FRM}	350	mA
Non-repetitive peak forward surge current @ t = 8.3ms	I _{FSM}	750	mA
Power dissipation	P _D	200	mW
Thermal resistance junction to ambient (Note 1)	R _{θJA}	500	°C/W
Operating junction temperature range	T _J	-40 to +125	°C
Storage temperature range	T _{STG}	-55 to +150	°C

Electrical characteristics (AT T_A=25°C unless otherwise noted)

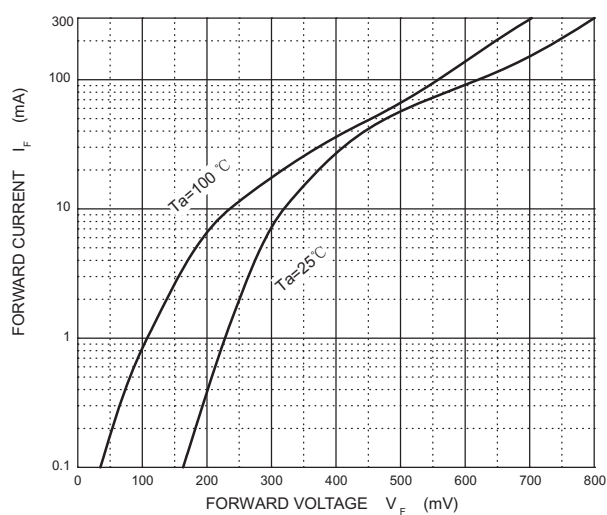
Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Reverse breakdown voltage (Note 2) I _R = 100μA	V _{BR}	100			V
Forward voltage (Note 2) I _F = 0.1mA I _F = 10mA I _F = 250mA	V _F			0.25 0.45 1.00	V
Reverse leakage current V _R = 1.5V V _R = 10V V _R = 50V V _R = 75V	I _R			0.3 0.5 1.0 2.0	μA
Diode capacitance V _R = 0V, f = 1.0MHz V _R = 1V, f = 1.0MHz	C _T		20 12		pF

Notes 1: Part mounted on FR-4 board with recommended pad layout.

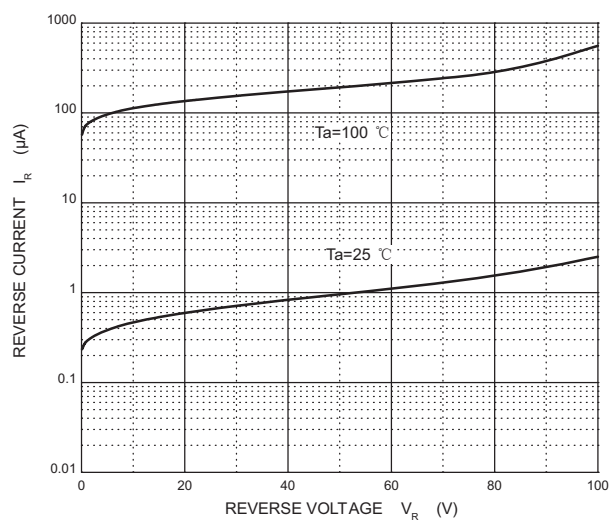
2: Short duration pulse test used to minimize self-heating effect.

Rating and characteristic curves (BAT46WS)

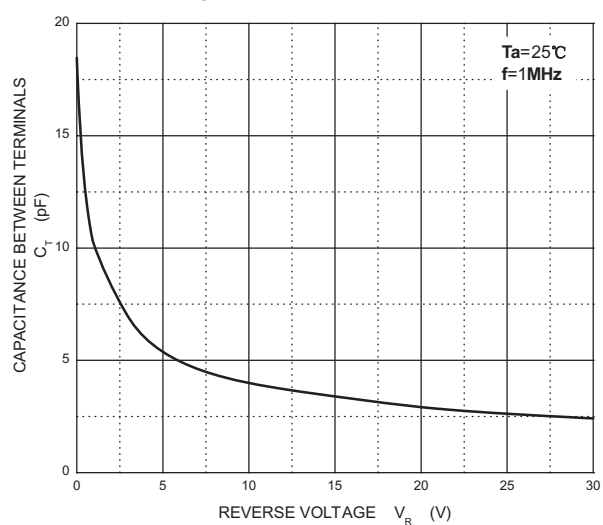
Forward Characteristics



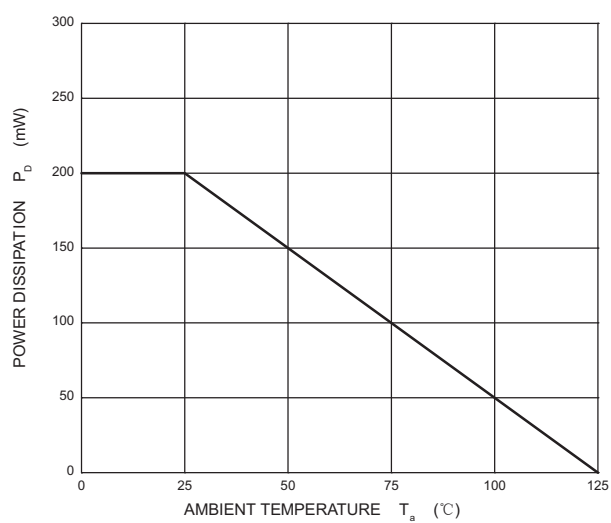
Reverse Characteristics



Capacitance Characteristics



Power Derating Curve



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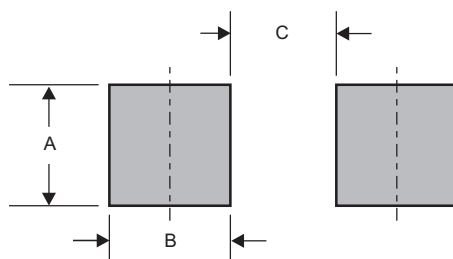
Pinning information

Pin	Simplified outline	Symbol
Pin1 cathode Pin2 anode		

Marking

Type number	Marking code
BAT46WS	S9,SO

Suggested solder pad layout

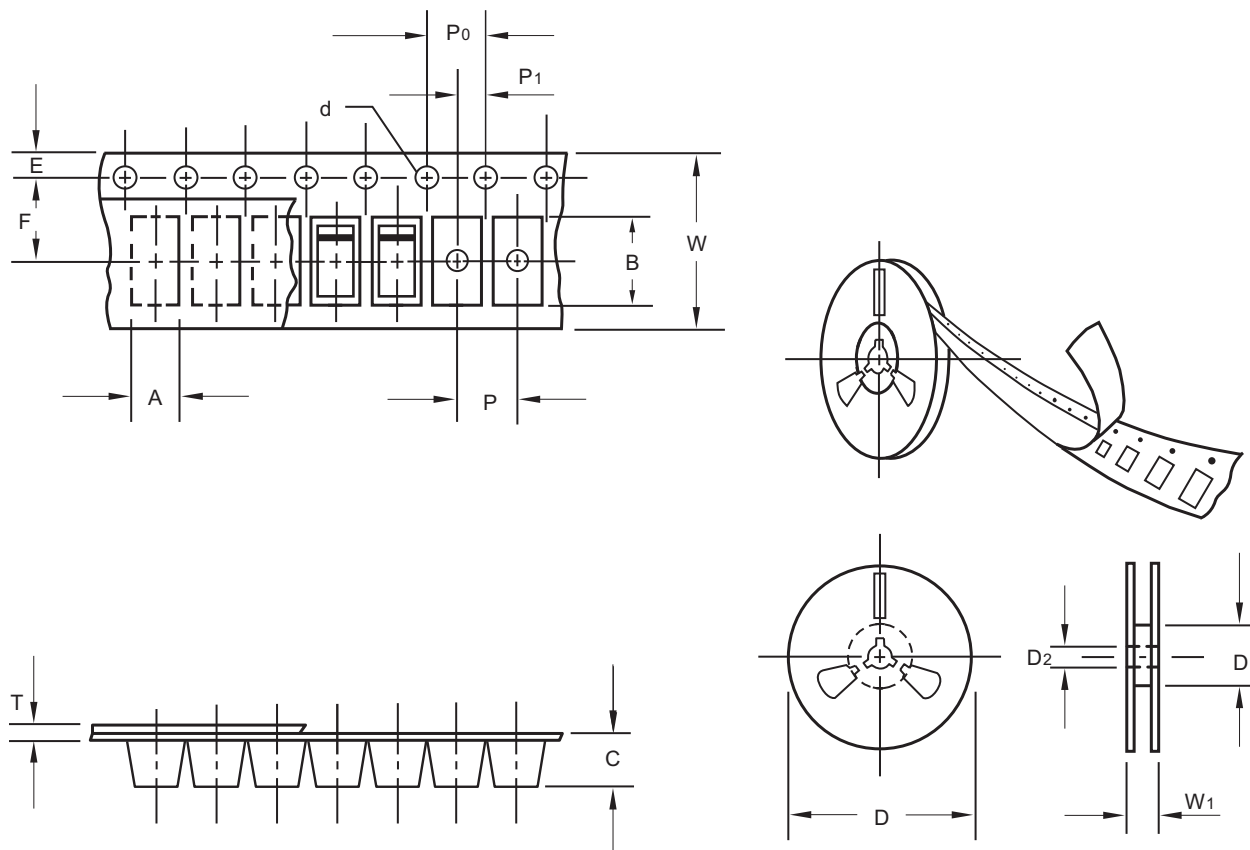


Dimensions in inches and (millimeters)

PACKAGE	A	B	C
SOD-323F	0.033 (0.83)	0.025 (0.63)	0.063 (1.60)

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Packing information



unit:mm

Item	Symbol	Tolerance	SOD-323F
Carrier width	A	0.1	1.48
Carrier length	B	0.1	3.30
Carrier depth	C	0.1	1.25
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D1	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D1	min	54.40
Feed hole diameter	D2	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P0	0.1	4.00
Embossment center	P1	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W1	1.0	12.3

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

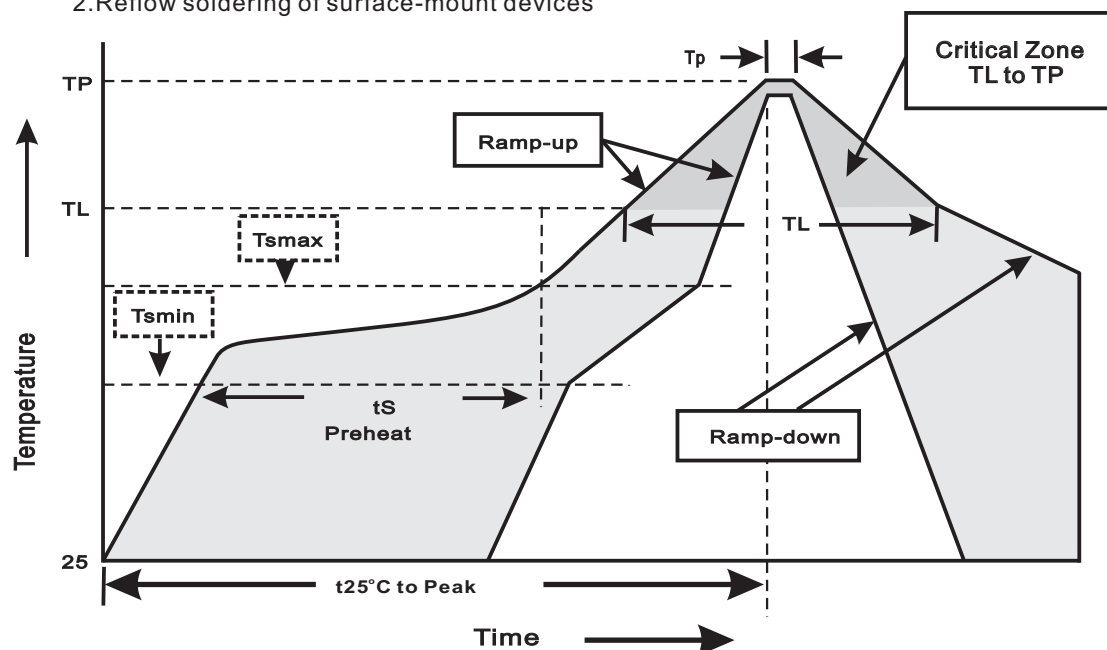
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Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOD-323F	7"	3,000	4.0	30,000	183*123*183	178	382*257*387	240,000	8.0

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	$<3^{\circ}\text{C}/\text{sec}$
Preheat -Temperature Min(T_{smin}) -Temperature Max(T_{smax}) -Time(min to max)(t_s)	150°C 200°C 60~120sec
T_{smax} to T_L -Ramp-upRate	$<3^{\circ}\text{C}/\text{sec}$
Time maintained above: -Temperature(T_L) -Time(t_L)	217°C 60~260sec
Peak Temperature(T_P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t_P)	10~30sec
Ramp-down Rate	$<6^{\circ}\text{C}/\text{sec}$
Time 25°C to Peak Temperature	$<6\text{minutes}$

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High reliability test capabilities

Item Test	Conditions	Reference
1. Solder Resistance	at $260 \pm 5^\circ\text{C}$ for $10 \pm 2\text{sec.}$	MIL-STD-750D METHOD-2031
2. Solderability	at $245 \pm 5^\circ\text{C}$ for 5 sec.	MIL-STD-202F METHOD-208
3. High Temperature Reverse Bias	$V_R = 80\%$ rate at $T_J = 125^\circ\text{C}$ for 168 hrs.	MIL-STD-750D METHOD-1038
4. Forward Operation Life	Rated average rectifier current at $T_A = 25^\circ\text{C}$ for 500hrs.	MIL-STD-750D METHOD-1027
5. Intermittent Operation Life	$T_A = 25^\circ\text{C}$, $I_F = I_O$ On state: power on for 5 min. off state: power off for 5 min. on and off for 500 cycles.	MIL-STD-750D METHOD-1036
6. Pressure Cooker	$15P_{SIG}$ at $T_A = 121^\circ\text{C}$ for 4 hrs.	JESD22-A102
7. Temperature Cycling	-55°C to $+125^\circ\text{C}$ dwelled for 30 min. and transferred for 5min. total 10 cycles.	MIL-STD-750D METHOD-1051
8. Forward Surge	Non-repetitive peak forward surge current	MIL-STD-750D METHOD-4066-2
9. Humidity	at $T_A = 85^\circ\text{C}$, RH=85% for 1000hrs.	MIL-STD-750D METHOD-1021
10. High Temperature Storage Life	at 175°C for 1000 hrs.	MIL-STD-750D METHOD-1031